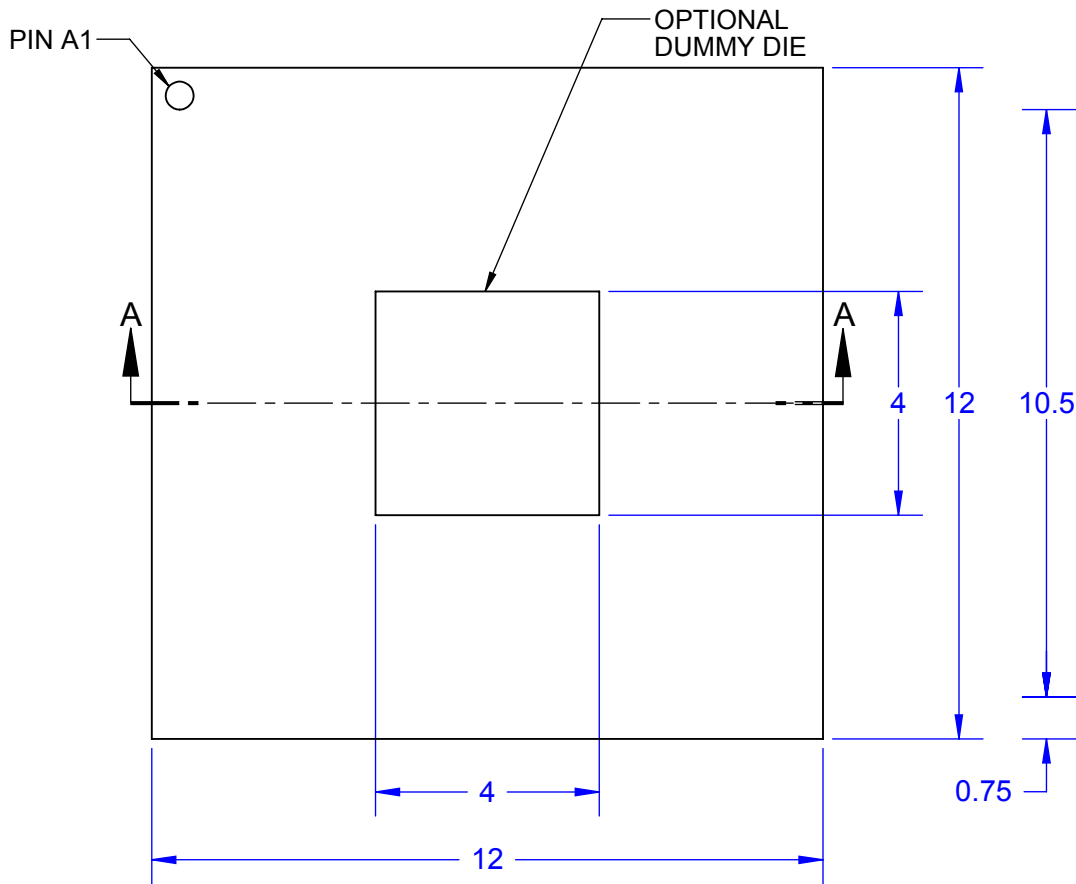
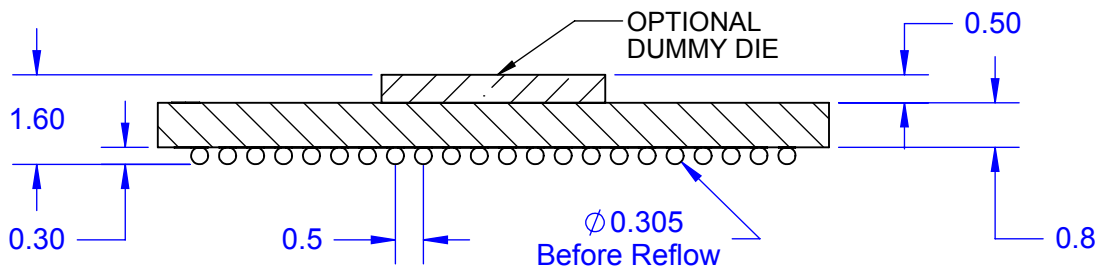
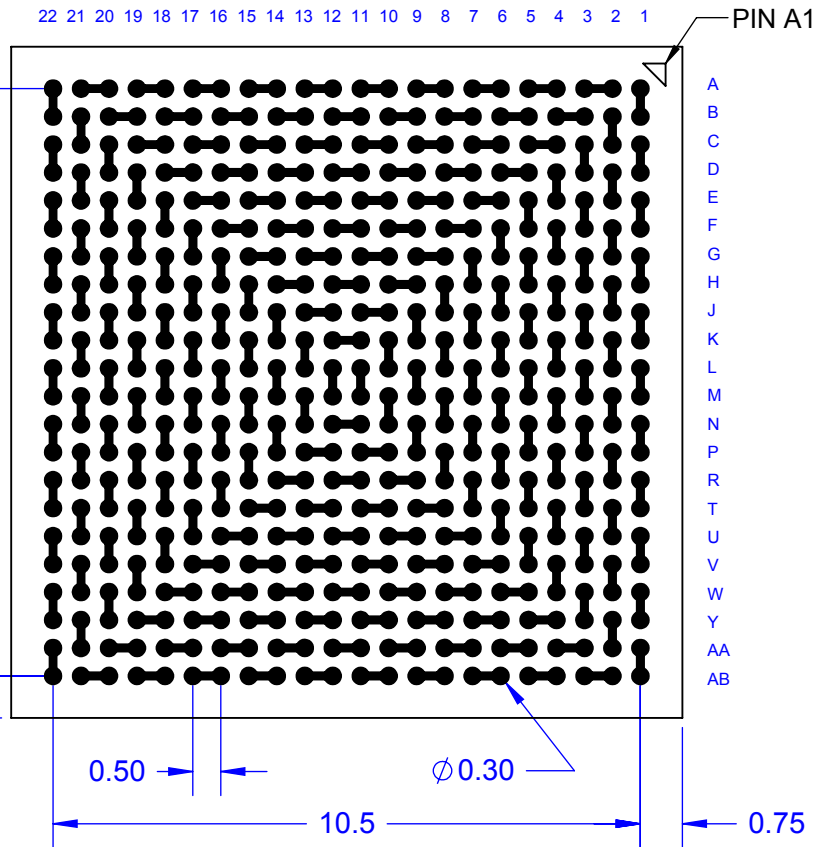


TOP VIEW



BALL VIEW



SECTION A-A

PART NUMBER TABLE

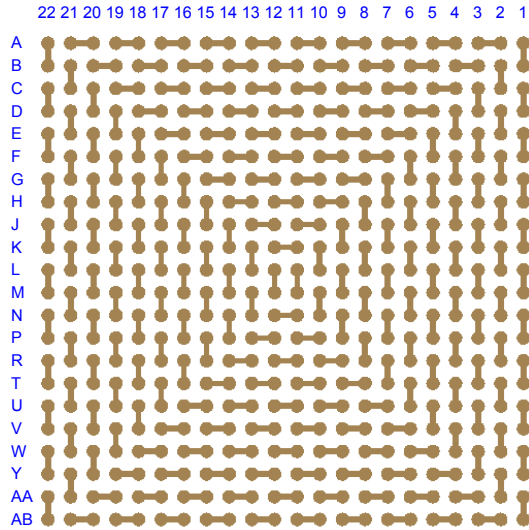
PART NUMBER	BALL ALLOY	Pb-Free	RoHS	Si DIE
LBGA484T.5C-DC229B	Sn96.5/Ag3.0/Cu0.5	YES	YES	NO
LBGA484T.5C-DC229BD	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES
LBGA484T.5-DC229B	Sn63/Pb37	NO	NO	NO
LBGA484T.5-DC229BD	Sn63/Pb37	NO	NO	YES

Notes: (Unless Otherwise Specified).

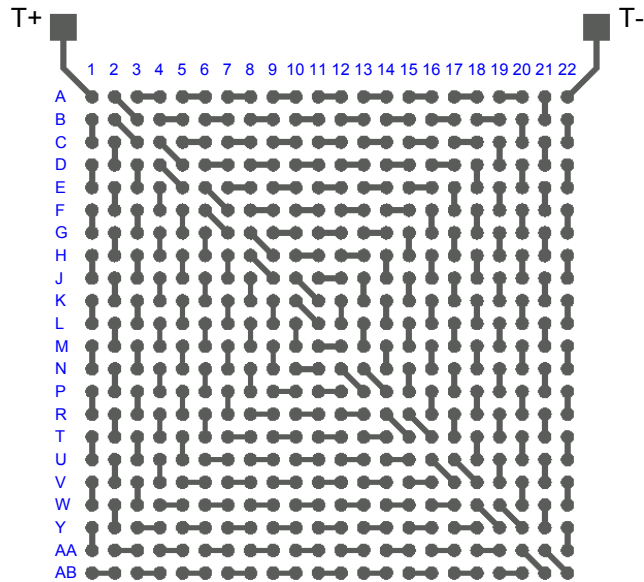
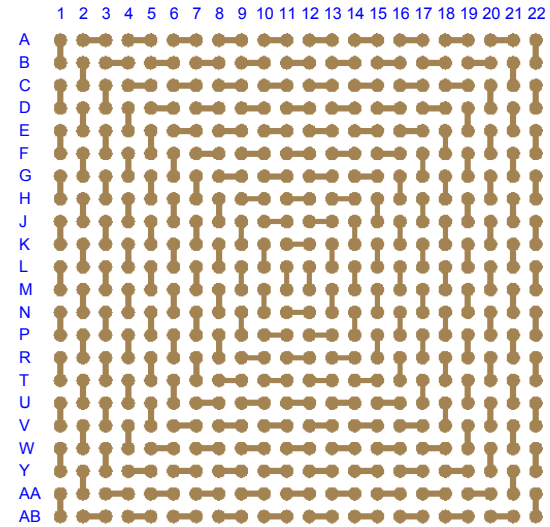
- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
- 3) BALL DIAMETER (BEFORE REFLOW): 0.30mm.
- 4) SOLDER MASK DEFINED PAD OPENING: 0.28mm (11 MIL).
- 5) PAD Cu DIAMETER: 0.355mm (14 MIL).
- 6) SUBSTRATE MATERIAL: BT (ALTERNATE FR4).
- 7) DUMMY DIE IS OPTIONAL.
- 8) DAISY CHAIN PATTERN (SEE PAGE 2).
- 9) MSL-3 RECOMMENDED BAKING 24 HOURS @ 125°C TO REMOVE MOISTURE PRIOR SOLDERING TO PC BOARD.

APPROVALS	DATE	TopLine®			
DRAWN T.Au	12/11/13	TITLE LBGA484T.5-DC229B DAISY CHAIN DUMMY			
ENG M. Hart	12/11/13				
MFG		SCALE 7.5:1	SIZE A	DRAWING NO. 552290	REV A
QA		DO NOT SCALE DRAWING			SHEET 1 OF 2
CUST					
REVISED					

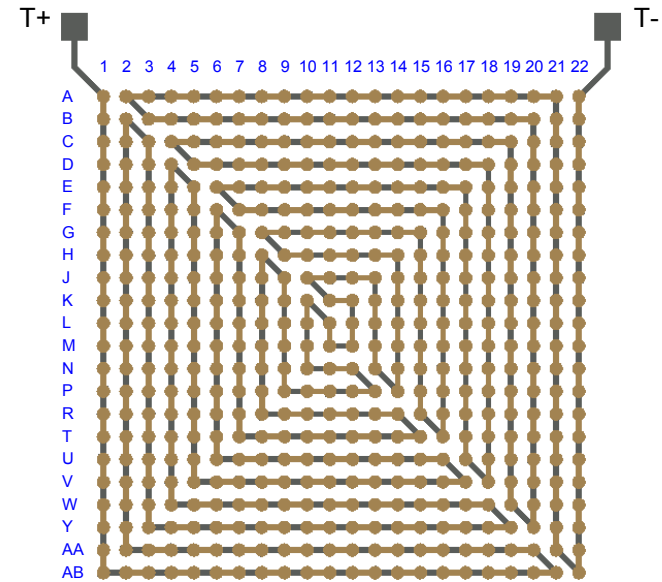
BALL VIEW



BOTTOM SIDE (TOP X-RAY VIEW)



TEST VEHICLE BOARD



AFTER MOUNTING

Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.355mm (14 MIL).
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.127mm (5 MIL).
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING: 0.28mm (11 MIL).

TopLine®			
TITLE		LBGA484T.5-DC229B DAISY CHAIN DUMMY	
SCALE	SIZE	DRAWING NO.	REV
6:1	A	552290	A
DO NOT SCALE DRAWING			SHEET 2 OF 2